MIC-6131

3U OpenVPX XMC carrier



Features

- OpenVPX MOD3-PER-1F-16.3.2-3 profile compliant
- Comply with VPX VITA 46.0, 46.4, 46.9 and VITA 48 spec
- High speed Data Plane interface up to PCle gen.3 x8
- Optional PCIe output up to gen. 3 x8
- XMC interface with X24S+X8D+X12D pin field
- Design to support the XMC card with 75W power consumption*

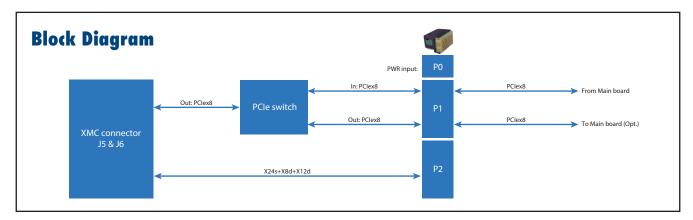


Introduction

MIC-6131 is a 3U OpenVPX XMC carrier. MIC-6131 complies with the MOD3-PER-1F-16.3.2-3 profile, and the VITA 46.0, 46.4, 46.9 and VITA 48 specification. The MIC-6131 Data Plane has the PCle Gen 3. Input, up to x8 lanes, and provides the optional PCle gen. 3 output with another x8 lanes. With this design, MIC-6131 is able to support the most powerful XMC with the 75W power consumption*, and doesn't sacrifice the full fabric bandwidth from the main board. For the XMC pin out, MIC-6131 has the X24S+X8D+X12D pin field on the VPX connector P2, and enables the vast capability of customization of the customer.

Specifications

VPX Interface	P0	Power: 12V only (default)
	P1	Data Plane 1x PCle x 8 + optional PCle output 1 x PCle x8
	P2	Optional X24S+X8D+X12D pin out
Front panel LED		Hot-Swap, Power
Power Requirement		Depends on the actual XMC power consumption
Physical Characteristics	Dimensions	160.00 x 100.00 mm (6.3" x 3. 95") (W x D), 5HP (H)
	Weight	To-be-measured kg without peripherals
Compliance	VPX	OpenVPX (VITA 65), REDI (VITA 48)
	Safety	FCC class A, CE, RoHS
	EMC	FCC47 CFR Part15, Class A, CE Mark (EN55022/EN55024/EN300386)



Related products

Product	Description
MIC-6330	3U OpenVPX CPU Blade with Intel® Xeon® Processor E3v5 and E3v6 family

Ordering Information

Model number	Configuration
MIC6131A000E-ES	MIC-6131 for convection cooled chassis
MIC6131C000E-ES	MIC-6131 with conduction cooled heatsink

^{*}The heat dissipation capacity depends on the actual chassis used.

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^{**} Please contact the Advantech representative for the availability.